

NON-PLANAR SURFACE FOR SEMICONDUCTOR CHIPS AND METHOD OF FORMING THE NON-PLANAR SEMICONDUCTOR CHIP

ABSTRACT

A semiconductor chip package (50) having a non-planar chip (58) therein, to reduce the stress concentrations between the chip (58) and cover plate (22). In particular, a chip (58) and method of forming a chip (58) having a non-planar or "domed" back surface (64), wherein the thickness of the non-planar chip (58) is greatest substantially near the centre of the chip (58). Further, a method of rounding the edges or corners of the chip (58) to reduce crack propagation originating at the edges of the chip (58).

FIG 2

